Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

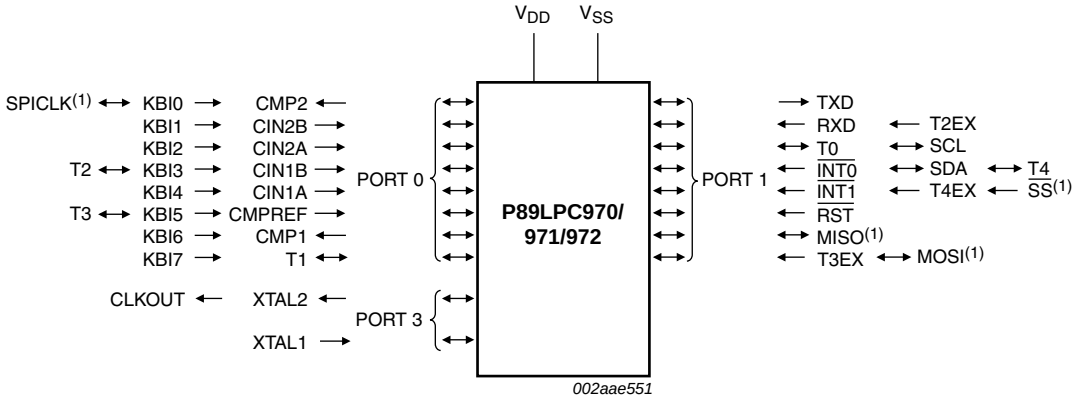
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc970fdh-129

2.2 Additional features

- A high performance 80C51 CPU provides instruction cycle times of 111 ns to 222 ns for all instructions except multiply and divide when executing at 18 MHz. This is six times the performance of the standard 80C51 running at the same clock frequency. A lower clock frequency for the same performance results in power savings and reduced EMI.
- Serial flash In-Circuit Programming (ICP) allows simple production coding with commercial EPROM programmers. Flash security bits prevent reading of sensitive application programs.
- Serial flash In-System Programming (ISP) allows coding while the device is mounted in the end application.
- In-Application Programming (IAP) of the flash code memory. This allows changing the code in a running application.
- Clock switching on the fly among internal RC oscillator, watchdog oscillator, external clock source provides optimal support of minimal power active mode with fast switching to maximum performance.
- Idle and two different power-down reduced power modes. Improved wake-up from Power-down mode (a LOW interrupt input starts execution). Typical power-down current is 1 μA (total power-down with voltage comparators disabled).
- Integrated PMU (Power Management Unit) automatically adjusts internal regulators to minimize power consumption during Idle mode, Power-down mode and total Power-down mode. In addition, the power consumption can be further reduced in Normal or Idle mode through configuring regulators modes according to the applications.
- Active-LOW reset. On-chip power-on reset allows operation without external reset components. A software reset function is also available.
- Configurable on-chip oscillator with frequency range options selected by user programmed flash configuration bits. Oscillator options support frequencies from 20 kHz to the maximum operating frequency of 18 MHz.
- Oscillator fail detect. The watchdog timer has a separate fully on-chip oscillator allowing it to perform an oscillator fail detect function.
- Programmable port output configuration options: quasi-bidirectional, open drain, push-pull, input-only.
- High current sourcing/sinking (20 mA) on eight I/O pins (P0.3 to P0.7, P1.4, P1.6, P1.7). All other port pins have high sinking capability (20 mA). A maximum limit is specified for the entire chip.
- Port ‘input pattern match’ detect. Port 0 may generate an interrupt when the value of the pins match or do not match a programmable pattern.
- Controlled slew rate port outputs to reduce EMI. Outputs have approximately 10 ns minimum ramp times.
- Only power and ground connections are required to operate the P89LPC970/971/972 when internal reset option is selected.
- Four interrupt priority levels.
- Eight keypad interrupt inputs, plus two additional external interrupt inputs.
- Schmitt trigger port inputs.
- Second data pointer.
- Emulation support.

5. Functional diagram



(1) For pin remap

Fig 2. Functional diagram

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
	DIP20, TSSOP20		
P0.6/CMP1/KBI6	14	I/O	**P0.6 —** Port 0 bit 6. High current source.
		O	**CMP1 —** Comparator 1 output.
		I	**KBI6 —** Keyboard input 6.
P0.7/KBI7/T1	13	I/O	**P0.7 —** Port 0 bit 7. High current source.
		I	**KBI7 —** Keyboard input 7.
		I/O	**T1 —** Timer/counter 1 external count input or overflow output.
P1.0 to P1.7		I/O, I [1]	**Port 1:** Port 1 is an 8-bit I/O port with a user-configurable output type, except for three pins as noted below. During reset Port 1 latches are configured in the input-only mode with the internal pull-up disabled. The operation of the configurable Port 1 pins as inputs and outputs depends upon the port configuration selected. Each of the configurable port pins are programmed independently. Refer to Section 7.16.1 “Port configurations” and Table 11 “Static characteristics” for details. P1.2 to P1.3 are open drain when used as outputs. P1.5 is input only. All pins have Schmitt trigger inputs. Port 1 also provides various special functions as described below:
P1.0/TXD	12	I/O	**P1.0 —** Port 1 bit 0.
		O	**TXD —** Transmitter output for serial port.
P1.1/RXD/T2EX	11	I/O	**P1.1 —** Port 1 bit 1.
		I	**RXD —** Receiver input for serial port.
		I	**T2EX —** Timer/counter 2 external capture input.
P1.2/SCL/T0	10	I/O	**P1.2 —** Port 1 bit 2 (open-drain when used as output).
		I/O	**SCL —** I^2C-bus serial clock input/output.
		I/O	**T0 —** Timer/counter 0 external count input or overflow output. (open-drain when used as output.)
P1.3/$\overline{\text{INT0}}$/SDA/T4	9	I/O	**P1.3 —** Port 1 bit 3 (open-drain when used as output).
		I	**$\overline{\text{INT0}}$ —** External interrupt 0 input.
		I/O	**SDA —** I^2C-bus serial data input/output.
		I/O	**T4 —** Timer/counter 4 external count input or overflow output.
P1.4/$\overline{\text{INT1}}$/T4EX/$\overline{\text{SS}}$	8	I/O	**P1.4 —** Port 1 bit 4. High current source.
		I	**$\overline{\text{INT1}}$ —** External interrupt 1 input.
		I	**T4EX —** Timer/counter 4 external capture input.
		I	**$\overline{\text{SS}}$ —** SPI Slave select input (pin remap).
P1.5/$\overline{\text{RST}}$	4	I	**P1.5 —** Port 1 bit 5 (input only).
		I	**$\overline{\text{RST}}$ —** External Reset input during power-on or if selected via UCFG1. When functioning as a reset input, a LOW on this pin resets the microcontroller, causing I/O ports and peripherals to take on their default states, and the processor begins execution at address 0. Also used during a power-on sequence to force ISP mode.
P1.6/MISO	3	I/O	**P1.6 —** Port 1 bit 6. High current source.
		I/O	**MISO —** SPI master in slave out. When configured as master, this pin is input, when configured as slave, this pin is output (pin remap).

7. Functional description

Remark: Please refer to the *P89LPC970/971/972 User manual* for a more detailed functional description.

7.1 Special function registers

Remark: SFR accesses are restricted in the following ways:

- User must **not** attempt to access any SFR locations not defined.
- Accesses to any defined SFR locations must be strictly for the functions for the SFRs.
- SFR bits labeled '-', '0' or '1' can **only** be written and read as follows:
  - '-' Unless otherwise specified, **must** be written with '0', but can return any value when read (even if it was written with '0'). It is a reserved bit and may be used in future derivatives.
  - '0' **must** be written with '0', and will return a '0' when read.
  - '1' **must** be written with '1', and will return a '1' when read.

Table 4. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
RCAP2L	Capture register 2 low byte	FBH									00	0000 0000
RCAP3H	Capture register 3 high byte	ECH									00	0000 0000
RCAP3L	Capture register 3 low byte	EBH									00	0000 0000
RCAP4H	Capture register 4 high byte	CAH									00	0000 0000
RCAP4L	Capture register 4 low byte	C9H									00	0000 0000
RSTSRC	Reset source register	DFH	-	BOIF	BORF	POF	R_KB	R_WD	R_SF	R_EX	[3]	
RTCCON	RTC control	D1H	RTCF	RTCS1	RTCS0	-	-	-	ERTC	RTCEN	60[2][4]	011x xx00
RTCH	RTC register high	D2H									00[4]	0000 000 0
RTCL	RTC register low	D3H									00[4]	0000 000 0
SADDR	Serial port address register	A9H									00	0000 000 0
SADEN	Serial port address enable	B9H									00	0000 000 0
SBUF	Serial port data buffer register	99H									xx	xxxx xxxx
		Bit address	**9F**	**9E**	**9D**	**9C**	**9B**	**9A**	**99**	**98**		
SCON*	Serial port control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00	0000 000 0
SSTAT	Serial port extended status register	BAH	DBMOD	INTLO	CIDIS	DBISEL	FE	BR	OE	STINT	00	0000 000 0
SP	Stack pointer	81H									07	0000 0111
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 010 0

Table 4. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
TH4	Timer/Counter 4 high byte	CCH									00	0000 0000
TL4	Timer/Counter 4 low byte	CBH									00	0000 0000
TINTF	Timer/Counters 2/3/4 overflow and external flags	CEH	-	-	TF4	EXF4	TF3	EXF3	TF2	EXF2	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0	[4][5]	
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK	[4][6]	
WDL	Watchdog load	C1H									FF	1111 1111
WFEED1	Watchdog feed 1	C2H										
WFEED2	Watchdog feed 2	C3H										

[1] BRGR1 and BRGR0 must only be written if BRGEN in BRGCON SFR is logic 0. If any are written while BRGEN = 1, the result is unpredictable.

[2] All ports are in input only (high-impedance) state after power-up.

[3] The RSTSRC register reflects the cause of the P89LPC970/971/972 reset except BOIF bit. Upon a power-up reset, all reset source flags are cleared except POF and BOF; the power-on reset value is x011 0000.

[4] The only reset sources that affect these SFRs are power-on reset and watchdog reset.

[5] On power-on reset and watchdog reset, the TRIM SFR is initialized with a factory preprogrammed value. Other resets will not cause initialization of the TRIM register.

[6] After reset, the value is 1110 01x1, i.e., PRE2 to PRE0 are all logic 1, WDRUN = 1 and WDCLK = 1. WDTOF bit is logic 1 after watchdog reset and is logic 0 after power-on reset. Other resets will not affect WDTOF.

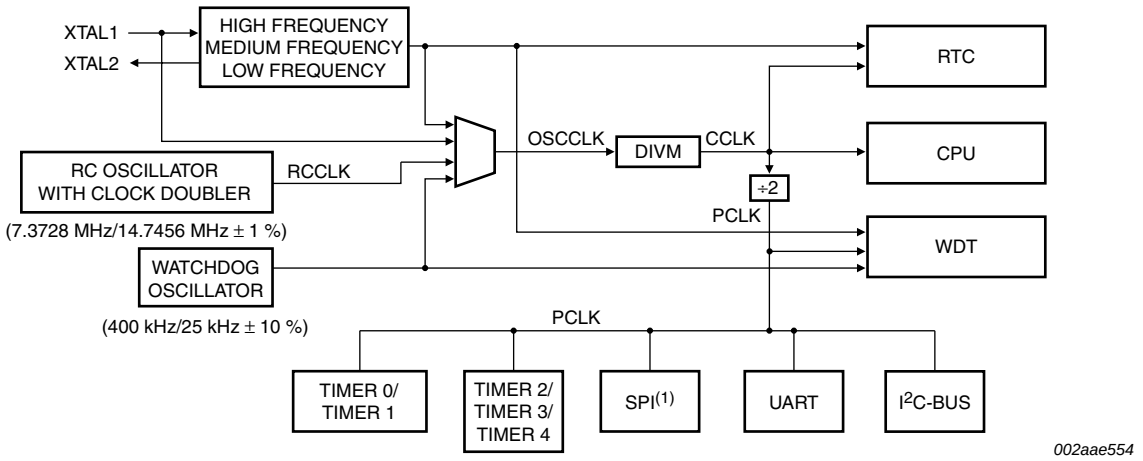
Table 5. Extended special function registers[1]

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
BODCFG	BOD configuration register	FFC8H	-	-	-	-	-	BOICFG2	BOICFG1	BOICFG0	[2]	
CLKCON	Clock control register	FFDEH	CLKOK	-	WDMOD	XTALWD	CLKDBL	FOSC2	FOSC1	FOSC0	[3]	1000 xxxx
CMPREF	Comparator reference register	FFCBH	-	REFS5	REFS4	REFS3	-	REFS2	REFS1	REFS0	00	0000 0000
RTCDATH	Real-time clock data register high	FFBFH									00	0000 0000
RTCDATL	Real-time clock data register low	FFBEH									00	0000 0000

[1] Extended SFRs are physically located on-chip but logically located in external data memory address space (XDATA). The MOVX A,@DPTR and MOVX @DPTR,A instructions are used to access these extended SFRs.

[2] The BOICFG2/1/0 will be copied from UCFG1.5 to UCFG1.3 when power-on reset.

[3] CLKCON register reset value comes from UCFG1. The reset value of CLKCON.2 to CLKCON.0 come from UCFG1.2 to UCFG1.0 and reset value of CLKDBL bit comes from UCFG1.7.



(1) ±10 % at 400 kHz.

Fig 5. Block diagram of oscillator control

7.10 CCLK wake-up delay

The P89LPC970/971/972 has an internal wake-up timer that delays the clock until it stabilizes depending on the clock source used. If the clock source is any of the three crystal selections (low, medium and high frequencies) the delay is 1024 OSCCLK cycles plus 60 μs to 100 μs. If the clock source is the internal RC oscillator, the delay is 200 μs to 300 μs. If the clock source is watchdog oscillator or external clock, the delay is 32 OSCCLK cycles.

7.11 CCLK modification: DIVM register

The OSCCLK frequency can be divided down up to 510 times by configuring a dividing register, DIVM, to generate CCLK. This feature makes it possible to temporarily run the CPU at a lower rate, reducing power consumption. By dividing the clock, the CPU can retain the ability to respond to events that would not exit Idle mode by executing its normal program at a lower rate. This can also allow bypassing the oscillator start-up time in cases where Power-down mode would otherwise be used. The value of DIVM may be changed by the program at any time without interrupting code execution.

7.12 Low power select

The P89LPC970/971/972 is designed to run at 18 MHz (CCLK) maximum. However, if CCLK is 8 MHz or slower, the CLKLP SFR bit (AUXR1.7) can be set to logic 1 to lower the power consumption further. On any reset, CLKLP is logic 0 allowing highest performance access. This bit can then be set in software if CCLK is running at 8 MHz or slower.

Table 8. SPI/I2C/UART pin remap

Peripherals	Function	Primary pin out	Alternative pin out
SPI	SPICLK	-	P0.0
	MOSI	-	P1.7
	MISO	-	P1.6
	$\overline{SS}$	-	P1.4
I2C	SDA	P1.3	-
	SCL	P1.2	-
UART	TXD	P1.0	-
	RXD	P1.1	-

7.17 Power management

The P89LPC970/971/972 support a variety of power management features.

Power-on detect and brownout detect are designed to prevent incorrect operation during initial power-up and power loss or reduction during operation.

The P89LPC970/971/972 support three different power reduction modes: Idle mode, Power-down mode, and total Power-down mode. In addition, individual on-chip peripherals can be disabled to eliminate unnecessary dynamic power use in any peripherals that are not required for the application.

Integrated PMU automatically adjusts internal regulators to minimize power consumption during Idle mode, Power-down mode and total Power-down mode. In addition, the power consumption can be further reduced in Normal or Idle mode through configuring regulators mode according to the applications.

7.17.1 Brownout detection

The brownout detect function determines if the power supply voltage drops below a certain level. Enhanced brownout detection has 3 independent functions: BOD reset, BOD interrupt and BOD flash.

These three functions are disabled in Power-down mode and Total Power-down mode. In Normal or Idle mode, BOD reset and BOD flash are always on and can not be disabled in software. BOD interrupt may be enabled or disabled in software.

BOD reset and BOD interrupt, each has 6 levels. BOE0 to BOE2 (UCFG1[3:5]) are used as trip point configuration bits of BOD reset. BOICFG0 to BOICFG2 in register BODCFG are used as trip point configuration bits of BOD interrupt.

BOD reset voltage should be lower than BOD interrupt trip point. BOD flash is used for flash programming/erase protection and has only 1 trip point at 2.4 V. Please refer to *P89LPC970/971/972 User manual* for detail configurations.

If brownout detection works, the brownout condition occurs when V_{DD} falls below the brownout falling trip voltage and is negated when V_{DD} rises above the brownout rising trip voltage.

For correct activation of brownout detect, the V_{DD} rise and fall times must be observed. Please see Table 11 “Static characteristics” for specifications.

7.18 Reset

The P1.5/$\overline{\text{RST}}$ pin can function as either a LOW-active reset input or as a digital input, P1.5. The Reset Pin Enable (RPE) bit in UCFG1, when set to logic 1, enables the external reset input function on P1.5. When cleared, P1.5 may be used as an input pin.

Remark: During a power-up sequence, the RPE selection is overridden and this pin always functions as a reset input. **An external circuit connected to this pin should not hold this pin LOW during a power-on sequence as this will keep the device in reset.** After power-up this pin will function as defined by the RPE bit. Only a power-up reset will temporarily override the selection defined by RPE bit. Other sources of reset will not override the RPE bit.

Reset can be triggered from the following sources:

- External reset pin (during power-up or if user configured via UCFG1)
- Power-on detect
- Brownout detect
- Watchdog timer
- Software reset
- UART break character detect reset

For every reset source, there is a flag in the Reset Register, RSTSRC. The user can read this register to determine the most recent reset source. These flag bits can be cleared in software by writing a logic 0 to the corresponding bit. More than one flag bit may be set:

- During a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- A Watchdog reset is similar to a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- For any other reset, previously set flag bits that have not been cleared will remain set.

7.18.1 Reset vector

Following reset, the P89LPC970/971/972 will fetch instructions from either address 0000H or the Boot address. The Boot address is formed by using the boot vector as the high byte of the address and the low byte of the address = 00H.

The boot address will be used if a UART break reset occurs, or the non-volatile boot status bit (BOOTSTAT.0) = 1, or the device is forced into ISP mode during power-on (see *P89LPC970/971/972 User manual*). Otherwise, instructions will be fetched from address 0000H.

7.19 Timers/counters 0 and 1

The P89LPC970/971/972 has two general purpose counter/timers which are upward compatible with the standard 80C51 Timer 0 and Timer 1. Both can be configured to operate either as timers or event counters. An option to automatically toggle the T0 or T1 pins upon timer overflow has been added.

In the ‘Timer’ function, the register is incremented every machine cycle.

7.26 KBI

The Keypad Interrupt function (KBI) is intended primarily to allow a single interrupt to be generated when Port 0 is equal to or not equal to a certain pattern. This function can be used for bus address recognition or keypad recognition. The port can be configured via SFRs for different tasks.

The Keypad Interrupt Mask Register (KBMASK) is used to define which input pins connected to Port 0 can trigger the interrupt. The Keypad Pattern Register (KBPATN) is used to define a pattern that is compared to the value of Port 0. The Keypad Interrupt Flag (KBIF) in the Keypad Interrupt Control Register (KBCON) is set when the condition is matched while the Keypad Interrupt function is active. An interrupt will be generated if enabled. The PATN_SEL bit in the Keypad Interrupt Control Register (KBCON) is used to define equal or not-equal for the comparison.

In order to use the Keypad Interrupt as an original KBI function like in P87LPC76x series, the user needs to set KBPATN = 0FFH and PATN_SEL = 1 (not equal), then any key connected to Port 0 which is enabled by the KBMASK register will cause the hardware to set KBIF and generate an interrupt if it has been enabled. The interrupt may be used to wake-up the CPU from Idle or Power-down modes. This feature is particularly useful in handheld, battery-powered systems that need to carefully manage power consumption yet also need to be convenient to use.

In order to set the flag and cause an interrupt, the pattern on Port 0 must be held longer than six CCLKs.

7.27 Watchdog timer

The watchdog timer causes a system reset when it underflows as a result of a failure to feed the timer prior to the timer reaching its terminal count. It consists of a programmable 12-bit prescaler, and an 8-bit down counter. The down counter is decremented by a tap taken from the prescaler. The clock source for the prescaler can be the PCLK, the nominal 400 kHz/25 kHz watchdog oscillator or low speed crystal oscillator. The watchdog timer can only be reset by a power-on reset. When the watchdog feature is disabled, it can be used as an interval timer and may generate an interrupt. Figure 15 shows the watchdog timer in Watchdog mode. Feeding the watchdog requires a two-byte sequence. If PCLK is selected as the watchdog clock and the CPU is powered down, the watchdog is disabled. The watchdog timer has a time-out period that ranges from a few μs to a few seconds. Please refer to the *P89LPC970/971/972 User manual* for more details.

7.29.6 ICP

ICP is performed without removing the microcontroller from the system. The ICP facility consists of internal hardware resources to facilitate remote programming of the P89LPC970/971/972 through a two-wire serial interface. The NXP ICP facility has made in-circuit programming in an embedded application - using commercially available programmers - possible with a minimum of additional expense in components and circuit board area. The ICP function uses five pins. Only a small connector needs to be available to interface your application to a commercial programmer in order to use this feature. Additional details may be found in the *P89LPC970/971/972 User manual*.

7.29.7 IAP

IAP is performed in the application under the control of the microcontroller's firmware. The IAP facility consists of internal hardware resources to facilitate programming and erasing. The NXP IAP has made in-application programming in an embedded application possible without additional components. Two methods are available to accomplish IAP. A set of predefined IAP functions are provided in a Boot ROM and can be called through a common interface, PGM_MTP. Several IAP calls are available for use by an application program to permit selective erasing and programming of flash sectors, pages, security bits, configuration bytes, and device ID. These functions are selected by setting up the microcontroller's registers before making a call to PGM_MTP at FF03H. The Boot ROM occupies the program memory space at the top of the address space from FF00H to FEFFH, thereby not conflicting with the user program memory space.

In addition, IAP operations can be accomplished through the use of four SFRs consisting of a control/status register, a data register, and two address registers. Additional details may be found in the *P89LPC970/971/972 User manual*.

7.29.8 ISP

ISP is performed without removing the microcontroller from the system. The ISP facility consists of a series of internal hardware resources coupled with internal firmware to facilitate remote programming of the P89LPC970/971/972 through the serial port. This firmware is provided by NXP and embedded within each P89LPC970/971/972 device. The NXP ISP facility has made in-system programming in an embedded application possible with a minimum of additional expense in components and circuit board area. The ISP function uses five pins (V_{DD}, V_{SS}, TXD, RXD, and $\overline{RST}$). Only a small connector needs to be available to interface your application to an external circuit in order to use this feature.

7.29.9 Power-on reset code execution

The P89LPC970/971/972 contains two special flash elements: the Boot Vector and the Boot Status bit. Following reset, the P89LPC970/971/972 examines the contents of the Boot Status bit. If the Boot Status bit is set to zero, power-up execution starts at location 0000H, which is the normal start address of the user's application code. When the Boot Status bit is set to a value other than zero, the contents of the Boot Vector are used as the high byte of the execution address and the low byte is set to 00H.

Table 9 shows the factory default Boot Vector setting for these devices. A factory-provided bootloader is pre-programmed into the address space indicated and uses the indicated bootloader entry point to perform ISP functions. This code can be erased by the user.

10. Dynamic characteristics

Table 12. Dynamic characteristics (12 MHz)

V_{DD} = 2.4 V to 5.5 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
$f_{osc(RC)}$	internal RC oscillator frequency	nominal f = 7.3728 MHz trimmed to ±1 % at T_{amb} = 25 °C; clock doubler option = OFF (default)	7.189	7.557	7.189	7.557	MHz
		nominal f = 14.7456 MHz; clock doubler option = ON, V_{DD} = 2.7 V to 5.5 V	14.378	15.114	14.378	15.114	MHz
$f_{osc(WD)}$	internal watchdog oscillator frequency		360	440	360	440	kHz
f_{osc}	oscillator frequency		0	12	-	-	MHz
$T_{cy(clk)}$	clock cycle time	see Figure 17	83	-	-	-	ns
f_{CLKLP}	low-power select clock frequency		0	8	-	-	MHz
Glitch filter							
t_{gr}	glitch rejection time	P1.5/$\overline{\text{RST}}$ pin	-	50	-	50	ns
		any pin except P1.5/$\overline{\text{RST}}$	-	15	-	15	ns
t_{sa}	signal acceptance time	P1.5/$\overline{\text{RST}}$ pin	125	-	125	-	ns
		any pin except P1.5/$\overline{\text{RST}}$	50	-	50	-	ns
External clock							
t_{CHCX}	clock HIGH time	see Figure 17	33	$T_{cy(clk)} - t_{CLCX}$	33	-	ns
t_{CLCX}	clock LOW time	see Figure 17	33	$T_{cy(clk)} - t_{CHCX}$	33	-	ns
t_{CLCH}	clock rise time	see Figure 17	-	8	-	8	ns
t_{CHCL}	clock fall time	see Figure 17	-	8	-	8	ns
Shift register (UART mode 0)							
T_{XLXL}	serial port clock cycle time	see Figure 18	$16T_{cy(clk)}$	-	1333	-	ns
t_{QVXH}	output data set-up to clock rising edge time	see Figure 18	$13T_{cy(clk)}$	-	1083	-	ns
t_{XHQX}	output data hold after clock rising edge time	see Figure 18	-	$T_{cy(clk)}$ + 20	-	103	ns
t_{XHDX}	input data hold after clock rising edge time	see Figure 18	-	0	-	0	ns
t_{XHDV}	input data valid to clock rising edge time	see Figure 18	150	-	150	-	ns
SPI interface							
f_{SPI}	SPI operating frequency						
	slave		0	$^{CCLK}/_{6}$	0	2.0	MHz
	master		-	$^{CCLK}/_{4}$	-	3.0	MHz

Table 12. Dynamic characteristics (12 MHz) *…continued*

V_{DD} = 2.4 V to 5.5 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
T_{SPICYC}	SPI cycle time	see Figure 19, 20, 21, 22					
	slave		$^{6}/_{CCLK}$	-	500	-	ns
	master		$^{4}/_{CCLK}$	-	333	-	ns
$t_{SPILEAD}$	SPI enable lead time	see Figure 21, 22					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 21, 22					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 19, 20, 21, 22					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 19, 20, 21, 22					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 19, 20, 21, 22					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 19, 20, 21, 22					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 21, 22					
	slave		0	120	0	120	ns
t_{SPIDIS}	SPI disable time	see Figure 21, 22					
	slave		0	240	-	240	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 19, 20, 21, 22					
	slave		-	240	-	240	ns
	master		-	167	-	167	ns
t_{SPIOH}	SPI output data hold time	see Figure 19, 20, 21, 22	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 19, 20, 21, 22					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 19, 20, 21, 22					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

Table 13. Dynamic characteristics (18 MHz)

V_{DD} = 3.6 V to 5.5 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$f_{osc(RC)}$	internal RC oscillator frequency	nominal f = 7.3728 MHz trimmed to ±1 % at T_{amb} = 25 °C; clock doubler option = OFF (default)	7.189	7.557	7.189	7.557	MHz
		nominal f = 14.7456 MHz; clock doubler option = ON	14.378	15.114	14.378	15.114	MHz
$f_{osc(WD)}$	internal watchdog oscillator frequency		360	440	360	440	kHz
f_{osc}	oscillator frequency		0	18	-	-	MHz
$T_{cy(clk)}$	clock cycle time	see Figure 17	55	-	-	-	ns
f_{CLKLP}	low-power select clock frequency		0	8	-	-	MHz
Glitch filter							
t_{gr}	glitch rejection time	P1.5/$\overline{RST}$ pin	-	50	-	50	ns
		any pin except P1.5/$\overline{RST}$	-	15	-	15	ns
t_{sa}	signal acceptance time	P1.5/$\overline{RST}$ pin	125	-	125	-	ns
		any pin except P1.5/$\overline{RST}$	50	-	50	-	ns
External clock							
t_{CHCX}	clock HIGH time	see Figure 17	22	$T_{cy(clk)} - t_{CLCX}$	22	-	ns
t_{CLCX}	clock LOW time	see Figure 17	22	$T_{cy(clk)} - t_{CHCX}$	22	-	ns
t_{CLCH}	clock rise time	see Figure 17	-	5	-	5	ns
t_{CHCL}	clock fall time	see Figure 17	-	5	-	5	ns
Shift register (UART mode 0)							
T_{XLXL}	serial port clock cycle time	see Figure 18	$16T_{cy(clk)}$	-	888	-	ns
t_{QVXH}	output data set-up to clock rising edge time	see Figure 18	$13T_{cy(clk)}$	-	722	-	ns
t_{XHQX}	output data hold after clock rising edge time	see Figure 18	-	$T_{cy(clk)}$ + 20	-	75	ns
t_{XHDX}	input data hold after clock rising edge time	see Figure 18	-	0	-	0	ns
t_{XHDV}	input data valid to clock rising edge time	see Figure 18	150	-	150	-	ns
SPI interface							
f_{SPI}	SPI operating frequency						
	slave		0	$^{CCLK}/_{6}$	0	3.0	MHz
	master		-	$^{CCLK}/_{4}$	-	4.5	MHz
T_{SPICYC}	SPI cycle time	see Figure 19, 20, 21, 22					
	slave		$^{6}/_{CCLK}$	-	333	-	ns
	master		$^{4}/_{CCLK}$	-	222	-	ns

11. Other characteristics

11.1 Comparator electrical characteristics

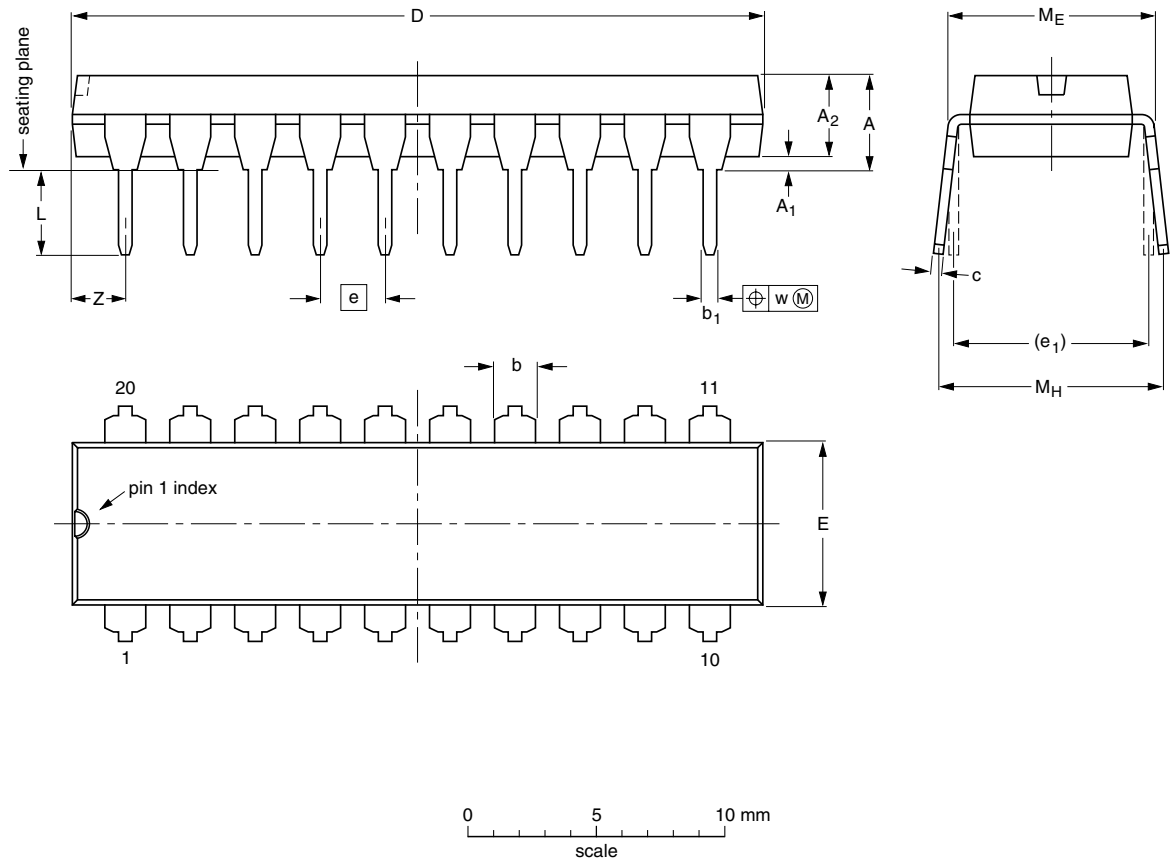
Table 15. Comparator electrical characteristics

V_{DD} = 2.4 V to 5.5 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IO}	input offset voltage			-	-	±10	mV
V_{IC}	common-mode input voltage			0	-	V_{DD} − 0.3	V
CMRR	common-mode rejection ratio		[1]	-	-	−50	dB
$t_{res(tot)}$	total response time			-	250	500	ns
$t_{(CE-OV)}$	chip enable to output valid time			-	-	10	μs
I_{LI}	input leakage current	0 V < V_I < V_{DD}		-	-	±1	μA

[1] This parameter is characterized, but not tested in production.

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT146-1		MS-001	SC-603			~~99-12-27~~ 03-02-13

Fig 25. DIP20 package outline (SOT146-1)

13. Abbreviations

Table 16. Abbreviations

Acronym	Description
CCU	Capture/Compare Unit
CPU	Central Processing Unit
CRC	Cyclic Redundancy Check
DAC	Digital to Analog Converter
EEPROM	Electrically Erasable Programmable Read-Only Memory
EMI	Electro-Magnetic Interference
EPROM	Erasable Programmable Read-Only Memory
GPIO	General Purpose Input/Output
IRC	Internal RC
LSB	Least Significant Bit
MSB	Most Significant Bit
PGA	Programmable Gain Amplifier
PLL	Phase-Locked Loop
PWM	Pulse Width Modulator
RAM	Random Access Memory
RC	Resistance-Capacitance
RTC	Real-Time Clock
SAR	Successive Approximation Register
SFR	Special Function Register
SPI	Serial Peripheral Interface
UART	Universal Asynchronous Receiver/Transmitter
WDT	Watchdog Timer

14. Revision history

Table 17. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
P89LPC97X v.3	20100608	Product data sheet	-	P89LPC97X_2
Modifications:	• Section 7.4 “Crystal oscillator option” on page 19: Updated text. • Section 7.27 “Watchdog timer” on page 40: Updated text.			
P89LPC97X_2	20100427	Product data sheet	-	P89LPC97X_1
Modifications:	• Changed data sheet status to ‘Product data sheet’. • Table 11 “Static characteristics”: Updated Min/Typ/Max values for BOD interrupt and BOD reset. • Table 11 “Static characteristics”: Updated conditions and Min/Max/Unit values for $(dV/dt)_r$.			
P89LPC97X_1	20091217	Preliminary data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

15.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

15.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.